## **Amendments to the Specification**

Please replace the paragraph on page 1, lines 20-25 with the following paragraph:

The conventional digital broadcast receiving tuner has a problem that it cannot be miniaturized partly because two tuners are individually manufactured, which causes low productivity and high cost, and partly because those two tuners are installed side by side on one surface of a mother board, which causes a large occupied-increases the size of the mother board area that is used for mounting the tuners.

Please replace the paragraphs beginning on page 2, line 5 and ending on page 3, line 12 with the following paragraphs:

As <u>a</u> first solving means solution to solve-the above-described problem, a structure is arranged such that the digital broadcast receiving tuner has an insulating board provided with a wiring pattern each on both surfaces thereof, and that on one surface of this insulating board there is formed a first tuner while on the other surface thereof there is formed a second tuner.

Also, as <u>a second solving means solution</u>, the insulating board is structured of a stacked multi-layer board, and the structure is arranged such that the first and second tuners are electrically shielded from each other by a grounding conductor layer provided within the multi-layer board.

Also, as a third solutionsolving means, a structure is arranged such that the first and second tuners have a high-frequency unit and a demodulation unit respectively, and that the high-frequency unit of the first tuner and the demodulation unit of the second tuner, and the demodulation unit of the first tuner and the high-frequency unit of the second tuner are arranged at a position opposite to each other with the multi-layer board interposed therebetween respectively.

Also, as <u>a</u> fourth <u>solutionsolving means</u>, a structure is arranged such that the multi-layer board is formed of at least three layers; between the lamination layers, there are provided at least the two grounding conductor layers; in a region in which the high-frequency unit is provided, the grounding conductor layers arranged near the high-frequency unit are provided with a deletion unit; and in a range in which the

demodulation unit is provided, the grounding conductor layers arranged near the demodulation unit are provided with a first remainder to thereby increase a facing distance between the wiring pattern of the high-frequency unit and the first remainder.

Also, as <u>a</u> fifth <u>solution</u>solving means, a structure is arranged such that the high-frequency unit has an IC component having a direct conversion unit including an oscillator and a mixer, and that the grounding conductor layer arranged near the high-frequency unit is provided with a second remainder to oppose a lower portion of the IC component.

Please replace the paragraph on page 4, lines 2-12 with the following paragraph:

A description will be made of the drawings of the digital broadcast receiving tuner according to the present invention. Fig. 1 is a block diagram showing a digital broadcast receiving tuner according to the present invention, Fig. 2 is an enlarged cross-sectional view for a principal part showing an outline of the digital broadcast receiving tuner according to the present invention, Fig. 3 is an enlarged plan view for a principal part showing an outline of the digital broadcast receiving tuner according to the present invention, and Fig. 4 is an enlarged bottom view for a principal part showing an outline of the digital broadcast receiving tuner according to the present invention.

Please replace the paragraphs on page 5, lines 13-24 with the following paragraphs:

Next, with reference to Figs. 2 to 4, a description will be made of the structure of the digital broadcast receiving tuner according to the present invention. An insulating board 1, which is a circuit board, is a multi-layer board formed by stacking a plurality (three layers in this case) of boards 1a, 1b and 1c (see Fig. 2), and on both surfaces, namely, a surface and a back surface exposed of this insulating board 1, there are provided wiring patterns 2a (see Figs. 2 and 3) and 2b (see Figs. 2 and 4).

Thus, on one surface side, which is the surface of this insulating board 1, there is formed the first tuner T1 (see Figs. 2 and 3) for a television, and on the other

surface side, which is the back surface, there is formed the second tuner T2 (see Figs. 2 and 4) for a VCR.

Please replace the paragraph on page 6, lines 20-26 with the following paragraph:

Also, <u>as shown in Fig. 2</u>, between the lamination layers of the insulating board 1 formed into three layers by the boards 1a, 1b and 1c, there are provided two grounding conductor layers 5 and 6, and the grounding conductor layer 5 provided between the board 1a and the board 1b is provided near the first tuner T1 side, while the grounding conductor layer 6 provided between the board 1b and the board 1c is provided near the second tuner T2 side.

Please replace the paragraph beginning on page 10, line 17 and ending on page 11, line 4 as follows:

Also, the multi-layer board is formed of at least three layers; between the lamination layers, there are provided at least two grounding conductor layers 5 and 6; in a region R1 in which the high-frequency unit is proved, the grounding conductor layers 5 and 6 arranged near the high-frequency unit are provided with deletion units 5b and 6b; and in a range-region R2 in which the demodulation unit is provided, the grounding conductor layers 5 and 6 arranged near the demodulation unit are provided with first remainders 5a and 6a to increase a facing distance between the wiring patterns 2a and 2b of the high-frequency unit and the first remainders 5a and 6a, and therefore, the capacitance between the wiring patterns 2a and 2b and the grounding conductor layers 5 and 6 can be reduced to thereby enhance the performance of the first and second tuners T1 and T2.